WaferSense®
Auto Gapping System (AGS)

Improve Uniformity and Yield with the Wireless WaferSense AGS for Accurate and Repeatable Setups

Speeds non-contact gap measurements and parallelism adjustments under vacuum for semiconductor processes such as thin-film deposition, sputtering and etch.

Achieve the ideal set-up for your equipment by measuring gaps at three points.

- Quickly achieve exactly the gap you need, using the chamber readings at process pressure in numerical and graphical form, with the easy-to-use GapView™ and GapReview™ software.
- Achieve the best uniformity, whether you need to set a gap that is perfectly parallel or slightly tilted.

Improve tool-to-tool process uniformity with objective and repeatable gap adjustments.

- Have peace of mind by taking the human variable out of adjusting your equipment.
- Make the right adjustments time after time.
- Enable anyone to set the same gap across the tools.

Reduce equipment calibration time through live feedback.

- See the effects of adjustments in real-time.
- Have a clear indication when equipment settings are within tolerance using measurements that can be taken from inside an evacuated process chamber.

Speed setups, maintenance and troubleshooting with automatic handling.

- Save time and expense.

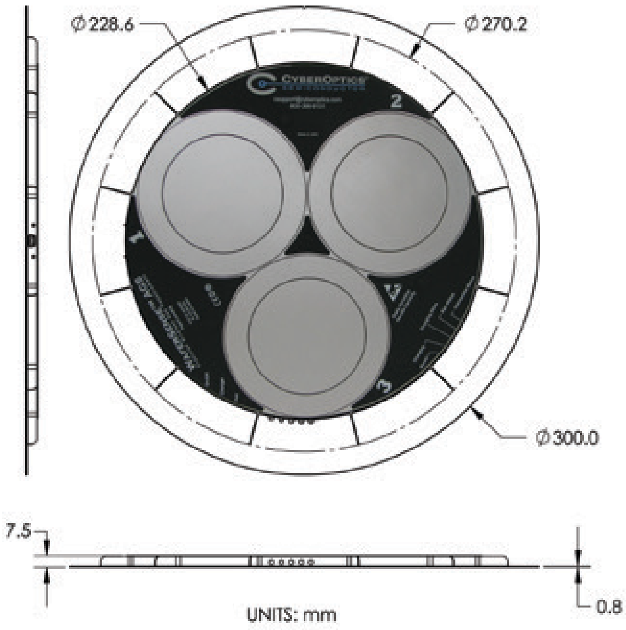
Semiconductor fabs and OEMs worldwide value the accuracy, precision and versatility of the WaferSense AGS – The most efficient and effective wireless measurement device for chamber gapping.

Save Time. Save Expense. Improve Yields.

Features

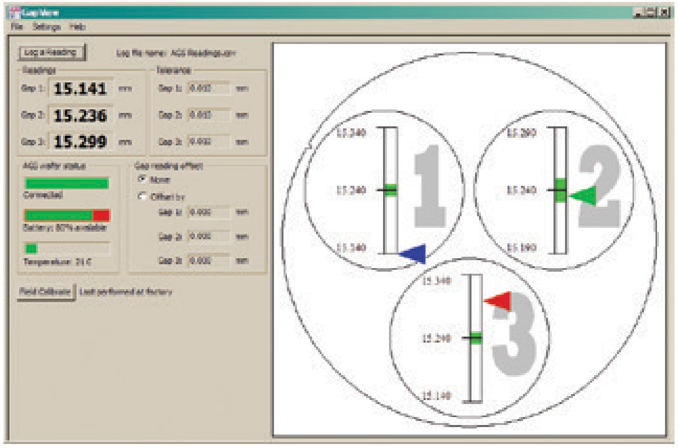
Wireless, wafer-shaped and battery-powered	Available in 200mm, 300mm and 450mm
Easy-to-use software	GapView and GapReview software included.
	GapView: Displays real-time numerical and graphical data. Easily identify if it is above, below or within the target gap range.
	GapReview: Replays log file data for review and analysis.
Highly accurate	Gap accuracy of +/-0.025 with gaps of 15mm within 4 hours of field calibration.
	Resolution of 0.005mm
Durable housing	Anodized aluminum (200 & 300mm), Carbon fiber composite (450mm)
Lightweight	225 grams (200mm), 400 grams (300mm), 750 grams (450mm)
Operating pressure	<10e^{-6} to 760 torr
Operating temperature	20 to 70 degrees C.
Battery-operation	>4 hrs. per charge, 8 hrs. typical
WaferSense Link	Bluetooth, 2.4 GHz, USB 1.1, dimensions 92mm x 58mm x 28mm
Operating Systems	Windows 7, XP and Vista
Product components	Gapping measurement device, charging clean case, carrying suitcase, USB communications link module and application software
Calibration	Factory recalibration recommended annually
Options	AGS15 Fixture with a NIST traceable gap used to check/set AGS gap measurement accuracy.
	AGS15L Field calibration fixture (for 450mm AGS).

Dimensions (AGS300)



Visit www.cyberoptics.com for drawings of other form factors.

GapView™



Gap 1: 15.141 mm
Gap 2: 15.236 mm
Gap 3: 15.299 mm

Real-time data.

Contact CyberOptics today for your complimentary on-tool demonstration
800.366.9131 or 763.542.5000 | CSsales@cyberoptics.com | www.cyberoptics.com

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